

JOINING METHOD AND CONDUCTIVE CIRCUIT STRUCTURE

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Inventor(s): LIU KUO-CHUAN; LEE MICHAEL G

Applicant(s): FUJITSU LTD

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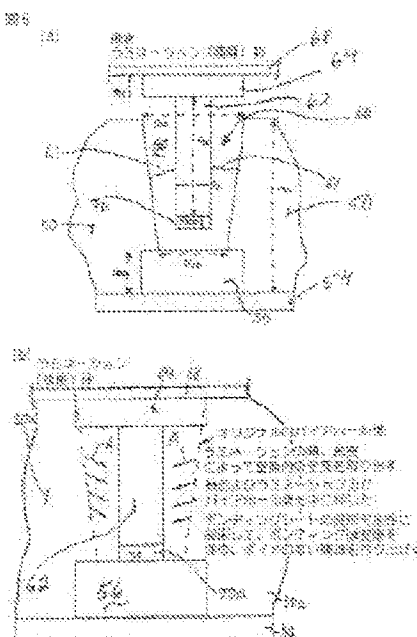
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Abstract of JP 2003124250 (A)

PROBLEM TO BE SOLVED: To provide a joining method comprising a stage for bonding a dielectric layer (preferably a bonding sheet) on a circuit forming layer having a conductive area. **SOLUTION:**

An aperture is formed in the dielectric layer on the conductive region. A conductive body, arranged on another circuit forming substrate, is inserted into the aperture. The conductive body comprises a main region (a conductive post, for example) and a depletion region (the thin layer of a metal or a transient liquid metal bonding material, for example). The depletion region is contacted with the conductive region on the circuit forming layer while these circuit forming layers are joined and laminated. Heat and pressure are applied on the combination to form an intermetal region from the depletion region.



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